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Part Number:

0737710100

Status:

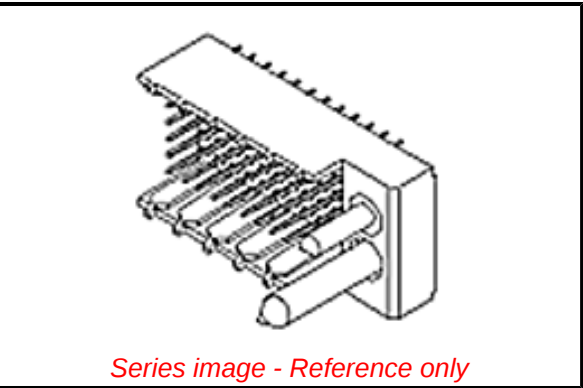
Active

Overview:

HDM Backplane Connector System

Description:

HDM Board-to-Board Stacking Header, High Rise Vertical, SMC, Press-Fit, Guide Pin Option, Keying Option A, 72 Circuits, Stack Height 15.05mm



Documents:

3D Model

Packaging Specification PK-70873-0870 (PDF)

Drawing (PDF)

RoHS Certificate of Compliance (PDF)

Product Specification PS-73780-999-001 (PDF)

Agency Certification	
CSA	LR19980
UL	E29179
General	
Product Family	Backplane Connectors
Series	73771
Application	Midplane
Component Type	PCB Header
Overview	HDM Backplane Connector System
Product Name	HDM
UPC	800754007559
Physical	
Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black
Durability (mating cycles max)	250
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	Yes
Material - Metal	Phosphor Bronze, Stainless Steel
Material - Plating Mating	Gold
Material - Plating Termination	Tin-Lead
Material - Resin	High Temperature Thermoplastic
Net Weight	15.470/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.381µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +105°C
Termination Interface: Style	Through Hole - Compliant Pin
Electrical	
Current - Maximum per Contact	1.0A

EU ELV	
Not Relevant	
EU RoHS	China RoHS
Compliant	
REACH SVHC	
Not Contained Per - ED/71/2019 (16 July 2019)	
Halogen-Free	
Status	
Low-Halogen	
For more information, please visit Contact US	
China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

73771 Series

Mates With

73632 HDM+ Board-to-Board Daughterboard Receptacle, 73780 HDM Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global	
Description	Product #
Extraction Tool	621001000
Backplane Insertion	621001400
Signal Contact Tool	
Backplane Signal	622008502
Insertion Module	
Press-In Tool for 2.00mm Pitch HDM*	
Board-to-Board	
Backplane Header	

Data Rate	1.0 Gbps
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0870
Product Specification	PS-73780-999-001
Sales Drawing	SD-73771-001

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